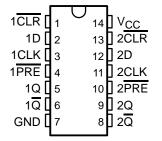
CD54ACT74, CD74ACT74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SCHS321 - DECEMBER 2002

- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54ACT74...F PACKAGE CD74ACT74...E OR M PACKAGE (TOP VIEW)



description/ordering information

The 'ACT74 dual positive-edge-triggered devices are D-type flip-flops.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – E	Tube	CD74ACT74E	CD74ACT74E		
–55°C to 125°C	SOIC – M	Tube	CD74ACT74M	ACT74M		
-55°C to 125°C	SOIC - IVI	Tape and reel	CD74ACT74M96	AC174W		
	CDIP – F	Tube	CD54ACT74F3A	CD54ACT74F3A		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each flip-flop)

	INP	OUTI	PUTS		
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н†	н†
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q_0	\overline{Q}_0

[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

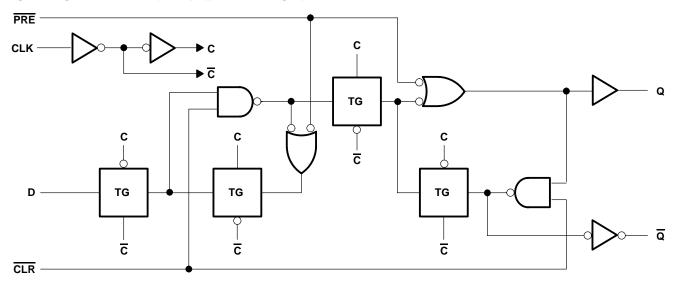


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logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	
M package	
Storage temperature range, T _{sto}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		T _A = 1	25°C	–55°0 125		–40°0 85°		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	0	VCC	V
٧o	Output voltage	0	VCC	0	VCC	0	VCC	V
ІОН	High-level output current		-24		-24		-24	mA
loL	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



CD54ACT74, CD74ACT74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	v _{cc}	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT		
			MIN	MAX	MIN	MAX	MIN	MAX			
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
Vou	V _I = V _{IH} or V _{IL}	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		V	
VOH	I vI = vIH or vIL	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				V	
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85			
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1		
\/a.		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μΑ	
Δl _{CC} ‡	$V_{I} = V_{CC} - 2.1 \text{ V}$		4.5 V to 5.5 V		2.4		3		2.8	mA	
C _i					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. ‡ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
Data	0.53
PRE or CLR	0.58
CLK	1

Unit load is $\triangle I_{CC}$ limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			–55°(125		–40°0 85°		UNIT	
			MIN	MAX	MIN	MAX		
fclock	Clock frequency			85		97	MHz	
	Pulse duration	PRE or CLR low	5		4.4		ns	
t _W	ruise duration	CLK	5.7		5			
	Catua tima	Data	4		3.5		ns	
t _{su}	Setup time	PRE or CLR inactive					ns	
th	Hold time	Data after CLK↑	0		0		ns	
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	2.7		2.4		ns	



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°(125		–40°(85°	UNIT	
	(01)	(6611 61)	MIN	MAX	MIN	MAX	
f _{max}			85		97		MHz
^t PLH	CLK	0 0	2.4	9.5	2.5	8.6	nc
^t PHL	CLK	Q or Q	2.4	9.5	2.5	8.6	ns
^t PLH	PRE or CLR	Q or $\overline{\mathbb{Q}}$	2.9	11.5	3	10.5	ns
^t PHL	FRE OI CER	300	3.1	12.5	3.2	11.4	115

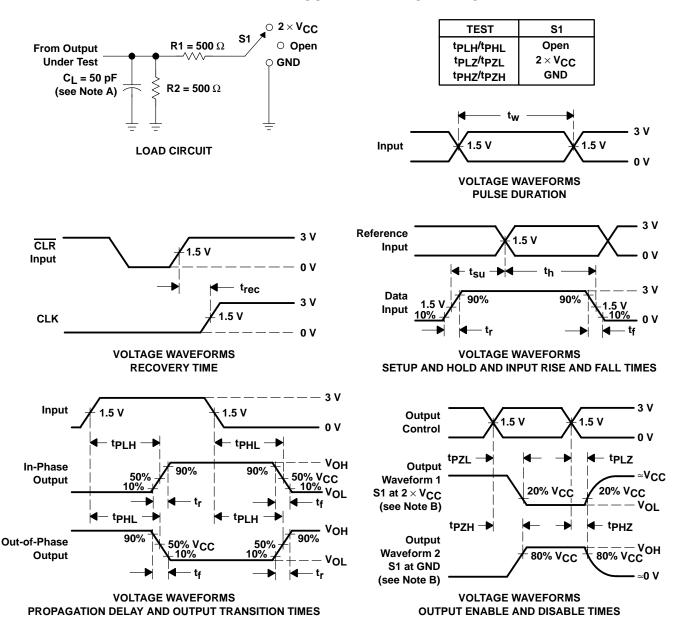
operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER T					
C _{pd}	Power dissipation capacitance	55	pF			



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. tpLZ and tpHZ are the same as tdis.

Figure 1. Load Circuit and Voltage Waveforms







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD54ACT74F3A	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	CD54ACT74F3A	Samples
CD74ACT74E	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT74E	Samples
CD74ACT74M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT74M	Samples
CD74ACT74M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT74M	Samples
CD74ACT74ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT74M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

6-Feb-2020

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OTHER QUALIFIED VERSIONS OF CD54ACT74, CD74ACT74:

Catalog: CD74ACT74

Automotive: CD74ACT74-Q1, CD74ACT74-Q1

Military: CD54ACT74

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

TAPE AND REEL INFORMATION





A0	<u> </u>
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT74M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

www.ti.com 26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT74M96	SOIC	D	14	2500	367.0	367.0	38.0

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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